

26th International Symposium on **Design & Diagnostics of Electronic Circuits & Systems** May 3-5, 2023 | Tallinn, Estonia

https://ddecs2023.taltech.ee

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The International Symposium on Design and Diagnostics of Electronic Circuits and Systems (DDECS) provides a forum for exchanging ideas, discussing research results, and presenting practical applications in the areas of design, test, and diagnosis of nanoelectronic digital, analog, and mixedsignal circuits and systems. The 26th edition of the DDECS Symposium will be held in Tallinn, the capital of the Estonia, which is is one of the best-preserved medieval cities in Europe.

The areas of interest include (but are not limited to) the following topics:

Topic 1. Analog, Mixed Signal, RF and Sensors

- Wireless circuits and systems
- High-frequency circuits
- Sensor technologies

Topic 2. Digital Circuit and System Design

- Digital architectures for DNNs
- Al and edge computing architectures
- Neural architecture search (NAS)
- Autonomous systems
- VLSI circuits design
- SoC and NoC architectures
- FPGA, DSP, accelerators

Topic 3. Test, Verification and Dependability

- Circuits and systems test
- Reliability and robustness of DNNs
- Fault-tolerance
- Self-health awareness and fault management
- Test infrastructures

Topic 4. Secure HW and Embedded Systems

- Cryptographic implementations
- Attacks against implementations
- Side-channel analysis

- RF design and test
- Analog neuromorphic circuits
- Analog and mixed-signal design and test
- Approximate computing
- High-performance computing
- Low-power design
- Embedded and cyber-physical systems
- **Embedded applications**
- EDA tools and methodologies
- ML-based EDA tools
- Diagnosis and debug
- Formal and simulation-based verification
- Functional safety
- Reliability
- ML-based test and dependability solutions
- Trusted computing platforms
- IP protection and reverse engineering
- Hardware Trojans

Topic 5. Emerging Technologies and New Computing Paradigms

- Brain-inspired computing
- Polymorphic and ambipolar circuits
- Reversible logic
- Quantum computing
- Quantum dot cellular automata
- Stochastic computing

- In-memory computing
- Memristor technology
- **Emerging memory devices**
- Silicon photonics
- Microfluidics and biochips
- DNA computing

Publication and submission:

DDECS 2023 seeks original, unpublished contributions of the following types:

- Regular Papers presenting novel and complete research work (6 pages)
- Student Papers from students eager to discuss their on-going research (4 pages)

DDECS review process is single-blind, i.e. the author information is not hidden. Accepted papers will be submitted for inclusion into IEEE Xplore.

Key dates

Submission deadline: January 15, 2023 Notification of acceptance: February 28, 2023